

Title (en)
Wafer planarization apparatus

Title (de)
Vorrichtung zur Planarisierung von Wafern

Title (fr)
Appareillage de planarisation de plaquette

Publication
EP 1263026 B1 20060809 (EN)

Application
EP 02011208 A 20020521

Priority
JP 2001150637 A 20010521

Abstract (en)
[origin: EP1263026A2] The wafer planarization apparatus (1) comprises a processing part (10) which holds a wafer (26) through a protective sheet (T) adhering to the obverse (26B) of the wafer (26) and processes the reverse (26A) of the wafer (26), an inspecting device (22) which inspects the wafer (26) having been processed by the processing part (10), a frame adhering part (108) which adheres a frame (F) through a sheet (S) to the reverse (26A) of the wafer (26) having been inspected by the inspecting device (22), a peeling part (112) which peels the protective sheet (T) from the wafer (26) to which the frame (F) has been adhered, and a transporting device (66, 118) which transports the wafer (26) between the processing part (10), the inspecting device (22), the frame adhering part (108), and the peeling part (112), so that the series of processing for the wafer (26) can be systematized in line. <IMAGE>

IPC 8 full level
B24B 49/02 (2006.01); **H01L 21/00** (2006.01); **B24B 7/00** (2006.01); **B24B 7/04** (2006.01); **B24B 7/10** (2006.01); **B24B 37/04** (2012.01); **H01L 21/302** (2006.01); **H01L 21/304** (2006.01); **H01L 21/66** (2006.01); **H01L 21/683** (2006.01)

CPC (source: EP KR US)
B24B 37/345 (2013.01 - EP US); **B24B 49/00** (2013.01 - EP US); **H01L 21/302** (2013.01 - KR); **H01L 21/67132** (2013.01 - EP US); **H01L 21/67155** (2013.01 - EP US); **H01L 21/67271** (2013.01 - EP US)

Cited by
EP1791162A1; US7757741B2; CN1299336C; EP1884990A4; US7503365B2

Designated contracting state (EPC)
DE FR GB IT NL

DOCDB simple family (publication)
EP 1263026 A2 20021204; **EP 1263026 A3 20040218**; **EP 1263026 B1 20060809**; DE 60213710 D1 20060921; DE 60213710 T2 20061214; JP 2002343756 A 20021129; KR 20020089180 A 20021129; MY 131229 A 20070731; SG 95694 A1 20030423; TW I253969 B 20060501; US 2002173229 A1 20021121; US 6863590 B2 20050308

DOCDB simple family (application)
EP 02011208 A 20020521; DE 60213710 T 20020521; JP 2001150637 A 20010521; KR 20020027849 A 20020520; MY PI20021857 A 20020521; SG 200203058 A 20020521; TW 91110660 A 20020521; US 14780302 A 20020520